



Material Content Data Sheet



Sales Product Name		BF 5030W H6327		Issued		25. September 2017		
MA#		MA000843316						
Package		PG-SOT343-4-1		Weight*		6.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.004	0.05		531	
	non noble metal	tin	7440-31-5	0.001	0.01		137	
	inorganic material	silicon	7440-21-3	0.027	0.39	0.45	3937	4605
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.68	49.89	496766	498862
wire	non noble metal	copper	7440-50-8	0.010	0.15	0.15	1458	1458
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4557	
	plastics	epoxy resin	-	0.660	9.80		97966	
	inorganic material	silicondioxide	60676-86-0	2.379	35.31	45.57	353134	455657
leadfinish	non noble metal	tin	7440-31-5	0.202	2.99	2.99	29938	29938
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9480	9480
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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